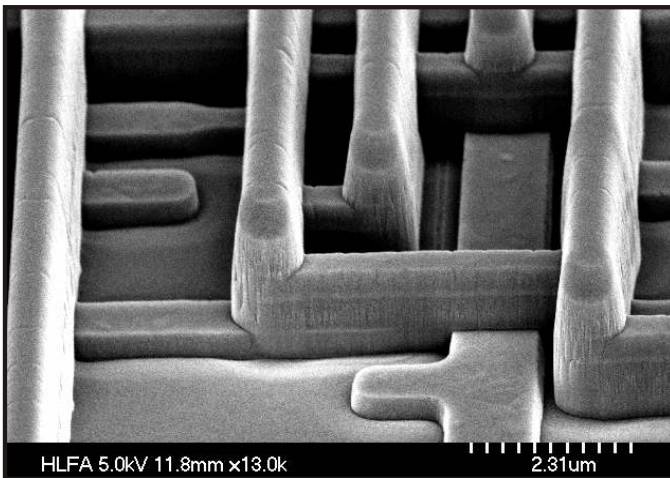
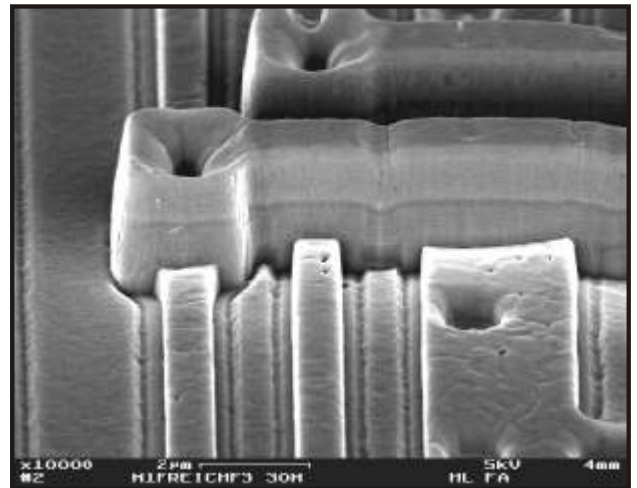
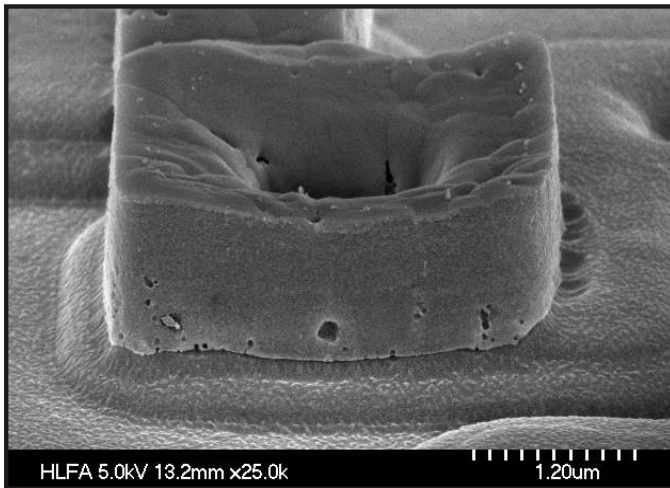


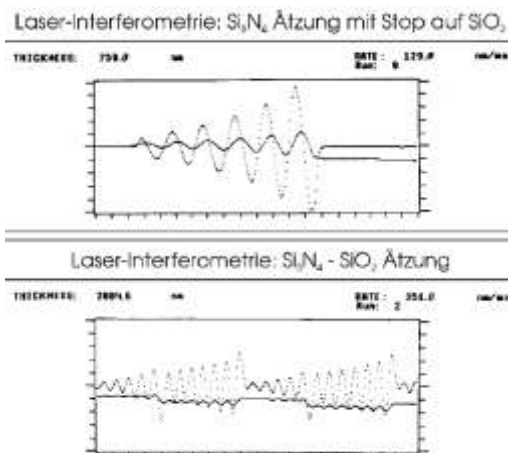
Plasmalab Data

Failure Analysis / Reverse Engineering



Courtesy of Infineon Munich:
0.35 and 0.7 μm techn
etched to M1 - M2 - M3

Equipment:
Plasmalab 80 Plus



Results:

- Isotropic Si_3N_4 removal with good selectivity to SiO_2 (and Al, Si)
- Anisotropic (or isotropic) Etch of SiO_2 with good selectivity to Si (and Al)
- Isotropic Al-Etch (or anisotropic)

Technology:

- 13 MHz - Plasma
- Laser Interferometry
- Planar / Plasma Etch (PE)
- Reactive Ion Etch (RIE)